

BCT48751

8:1 CMOS Analog Signal Multiplexer

GENERAL DESCRIPTION

The BCT48751 is a CMOS analog IC configured as an 8-channel multiplexer. This CMOS device can operate from 2.5V to 5.5V single supplies. Each switch can handle rail-to-rail analog signals. The off-leakage current is less then 1uA at 25°C. All digital inputs can support 1.8V logic control I/O.

APPLICATIONS

Battery-Operated Equipment
Audio and Video Signal Routing
Low-Voltage Data-Acquisition Systems
Communications Circuits
Automotive

FEATURES

- Guaranteed On-Resistance
 - 48Ω (TYP) with +5V Supply
- Guaranteed On-Resistance Match Between Channels
 - 1.5Ω (TYP) with +5V Supply
- High -3dB Bandwidth: 300MHz
- Low Off-Leakage Current 1uA (MAX) at 25°C
- Low On-Leakage Current 1uA (MAX) at 25°C
- 2.5V to 5.5V Single-Supply Operation
- 1.8V Logic Compatible
- High Off-Isolation:-83dB(RL=50Ω, f=1MHz)
- -40°C to 85°C Operating Temperature Range
- Available in Green QFN-3x3-16L , SOP16 , SSOP16 or TSSOP16 Packages

ORDERING INFORMATION

Order Number	Package Type	Temperature Range	Marking	QTY/Reel
			B	
BCT48751EGE-TR	QFN3x3-16L	-40°C to +85°C	48751	3000
			XXXXX	
			B	
BCT48751EOE-TU	SOP16	-40°C to +85°C	48751	
			XXXXX	
			B	
BCT48751EOE-TR	SOP16	-40°C to +85°C	48751	3000
			xxxxx	
			B	
BCT48751ESE-TU	SSOP16	-40°C to +85°C	48751	
			xxxx	
			B	
BCT48751ECE-TR	TSSOP16	-40°C to +85°C	48751	3000
			XXXXX	

Note: "XXXXX" in Marking will be appeared as the batch code.



ABSOLUTE MAXIMUM RATINGS

$\mbox{V}_{\mbox{\footnotesize CC}}$ to GND0.3V to +6.0V
Voltage into Any Terminal0.3V to (V $_{\text{CC}}\text{+ }0.3\text{V})$
Continuous Current into Any Terminal $\pm 20 \text{mA}$
Peak Current, X_
(Pulsed at 1ms, 10% duty cycle) $\pm 40 \text{mA}$
Storage Temperature Range65 $^{\circ}\!$
Junction Temperature150 $^{\circ}\mathrm{C}$
Operating Temperature Range40 $^{\circ}\!$
Lead Temperature (Soldering, 10 sec)260 $^{\circ}\mathrm{C}$
ESD Susceptibility
HBM2000V
MM200V

NOTE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

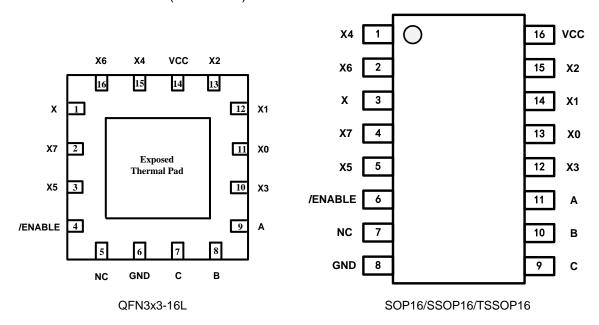
CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. Broadchip recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Broadchip reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time. Please contact Broadchip sales office to get the latest datasheet.



PIN CONFIGURATION (TOP VIEW)



PIN DESCRIPTION

PII	N			
QFN3x3-16L	SOP16 SSOP16 TSSOP16	NAME	FUNCTION	
11,12,13,10, 15,3,16,2	13,14,15,12 ,1,5,2,4	X0-X7	Analog Switch Inputs X0-X7.	
1	3	Х	Analog Switch "X" Output.	
14	16	V_{CC}	Positive Analog and Digital Supply Voltage Input.	
9	11	Α	Digital Address "A" Input.	
8	10	В	Digital Address "B" Input.	
7	9	С	Digital Address "C" Input.	
6	8	GND	Ground. Connect to digital ground.	
5	7	NC	No Connect.	
4	6	/ENABLE	Digital Enable Input. Normally connected to GND.	
Exposed Pad	-	EP	Exposed Pad. Connect EP to GND.	



FUNCTION TABLE

/ENABLE	S	ELECT INPUT	S	ON SWITCHES
INPUT	С	В	Α	ON SWITCHES
Н	Х	Х	Х	All Switches Open.
L	L	L	L	X-X0
L	L	L	Н	X-X1
L	L	Н	L	X-X2
L	L	Н	Н	X-X3
L	Н	L	L	X-X4
L	Н	L	Н	X-X5
L	Н	Н	L	X-X6
L	Н	Н	Н	X-X7

X=Don't care

NOTE: Input and output pins are identical and interchangeable. Either maybe considered an input or output; signals pass equally will in either direction.



ELECTRICAL CHARACTERISTICS

(V_{CC}= 5.0V, typical values are at T_A =+25 $^{\circ}$ C, unless otherwise specified.)

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS	
ANALOG SWITCH							
Analog Signal Range	V_{X-}, V_{X}		GND		V_{CC}	mV	
On-Resistance	R _{ON}	I _X =1mA		48	58	Ω	
On-Resistance Match Between Channels	ΔR_{ON}	I _X =1mA		1.5	5	Ω	
On-Resistance Flatness	R _{FLAT(ON)}	I _X =1mA		17	25	Ω	
X_ Off Leakage Current	I _{X_(OFF)}	V _X =4.5V or 0V			1	uA	
X Off Leakage Current	I _{X(OFF)}	V _X =4.5V or 0V			1	uA	
X On Leakage Current	I _{X(ON)}	V _X =4.5V or 0V			1	uA	
DIGITAL I/O						•	
Input Voltage High	V _{IH}	A,B,C,/ENABLE Pin	1.7			V	
Input Voltage Low	V _{IL}	A,B,C,/ENABLE Pin			0.5	V	
Input Current High	I _{IH}	V _A , V _B , V _C , V _{/ENABLE} =V _{CC}			1	uA	
Input Current Low	I _{IL}	V _A , V _B , V _C , V _{/ENABLE} =0V			1	uA	
DYNAMIC CHARACTERISTICS							
Address Transition Time	t _{TRANS}	$V_{X_{-}}=3V$, $R_{L}=300\Omega$, $C_{L}=35pF$		85		ns	
/ENABLE Turn-On Time	t _{ON}	$V_{X_{-}}=3V, R_{L}=300\Omega, C_{L}=35pF$		60		ns	
/ENABLE Turn-Off Time	t _{OFF}	$V_X=3V$, $R_L=300\Omega$, $C_L=35pF$		70		ns	
Internal A, B, C Rise Time	t _R	$V_{X_{-}}=3V$, $R_{L}=300\Omega$, $C_{L}=35pF$		45		ns	
Internal A, B, C Fall Time	t _F	$V_{X_{-}}=3V, R_{L}=300\Omega, C_{L}=35pF$		50		ns	
Break-Before-Make Time Delay	t _D	$V_{X_{-}}=3V, R_{L}=300\Omega, C_{L}=35pF$		50		ns	
Charge Injection	Q	$R_S=0\Omega$, $C_L=1$ nF		6		рС	
ANALOG SWITCH							
Input Off-Capacitance	C _{X_(OFF)}	V _{X_} =0V, f=1MHz		4.7		pF	
Output Off-Capacitance	$C_{X(OFF)}$	V _{X_} =0V, f=1MHz		12.7		pF	
Output On-Capacitance	$C_{X(ON)}$	V _{X_} =0V, f=1MHz		16		pF	
-3dB Bandwidth	BW	R _L =50Ω		300		MHz	
Off Isolation	O _{ISO}	RL=50Ω, f=1MHz		-83		dB	
Total Harmonic Distortion	THD	R_L =600 Ω , 5 V_{P_P} , f=20Hz to 20kHz		0.7		%	
Power Supply							
Power Supply Range	V _{CC}		2.5		5.5	V	
Power Supply Current	I _{CC}	V_{CC} =5V, V_A , V_B , V_C , $V_{/ENABLE}$ = V_{CC} or 0		0.001	6	uA	

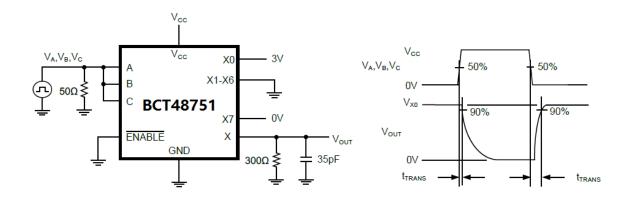


ELECTRICAL CHARACTERISTICS

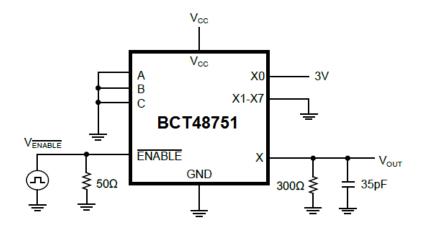
(V_{CC}= 3.3V, typical values are at T_A =+25 $^{\circ}$ C, unless otherwise specified.)

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
ANALOG SWITCH						
Analog Signal Range	V_{X-}, V_{X}		GND		V _{CC}	mV
On-Resistance	R _{ON}	I _X =1mA		80	110	Ω
X_ Off Leakage Current	I _{X_(OFF)}	V _X _=1V, 3V			1	uA
X Off Leakage Current	I _{X(OFF)}	V _X =1V, 3V			1	uA
X On Leakage Current	I _{X(ON)}	V _X =1V, 3V			1	uA
DIGITAL I/O						
Input Voltage High	V_{IH}		1.7			V
Input Voltage Low	V_{IL}				0.5	V
Input Current High	I _{IH}	V _A , V _B , V _C , V _{/ENABLE} =V _{CC}		1	1000	nA
Input Current Low	I _{IL}	V _A , V _B , V _C , V _{/ENABLE} =0V		1	1000	nA
DYNAMIC CHARACTERISTICS						
Address Transition Time	t _{TRANS}	$V_{X_{-}}=3V$, $R_{L}=300\Omega$, $C_{L}=35pF$		150		ns
/ENABLE Turn-On Time	t _{ON}	$V_{X_{-}}=3V$, $R_{L}=300\Omega$, $C_{L}=35pF$		110		ns
/ENABLE Turn-Off Time	t _{OFF}	$V_{X_{-}}=3V$, $R_{L}=300\Omega$, $C_{L}=35pF$		100		ns
Internal A, B, C Rise Time	t_R	$V_{X_{-}}=3V$, $R_{L}=300\Omega$, $C_{L}=35pF$		80		ns
Internal A, B, C Fall Time	t _F	$V_{X_{-}}=3V$, $R_{L}=300\Omega$, $C_{L}=35pF$		85		ns
Break-Before-Make Time Delay	t_D	$V_{X_{-}}=3V$, $R_{L}=300\Omega$, $C_{L}=35pF$		80		ns
ANALOG SWITCH						
-3dB Bandwidth	BW	$R_L=50\Omega$		300		MHz
Charge Injection	Q	$R_S=0\Omega$, $C_L=1nF$		6		рC
POWER SUPPLY						
Power Supply Current	I _{CC}	V_{CC} =5V, V_A , V_B , V_C , $V_{/ENABLE}$ = V_{CC} or 0		0.001	3	uA

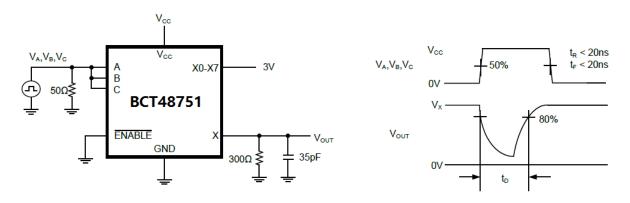
TEST CIRCUITS



Test Circuit 1. Address Transition Times (t_{TRANS})

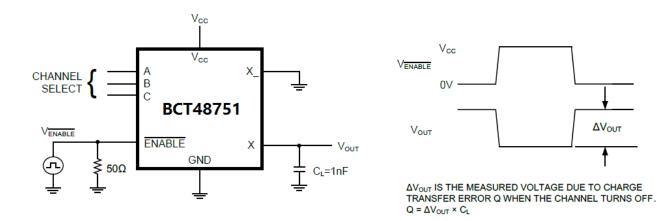


Test Circuit 2. Switching Times (ton, toff)

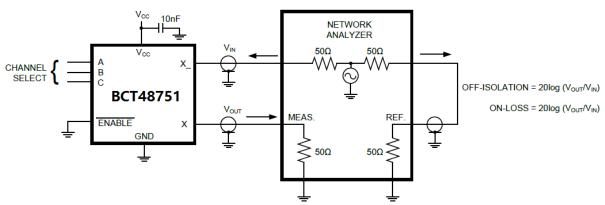


Test Circuit 3. Break-Before-Make Time Delay (t_D)

TEST CIRCUITS

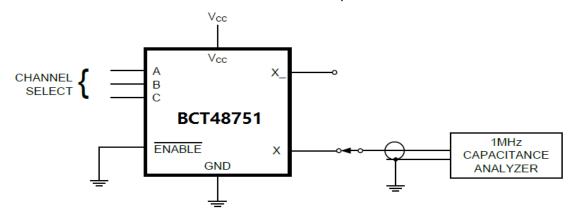


Test Circuit 4. Charge Injection (Q)



MEASUREMENTS ARE STANDARDIZED AGAINST SHORT AT SOCKET TERMINALS.
OFF-ISOLATION IS MEASURED BETWEEN COM AND "OFF" NO TERMINAL ON EACH SWITCH.
ON-LOSS IS MEASURED BETWEEN COM AND "ON" NO TERMINAL ON EACH SWITCH.
SIGNAL DIRECTION THROUGH SWITCH IS REVERSED; WORST VALUES ARE RECORDED.

Test Circuit 5. Off Isolation, On Loss



Test Circuit 6. Capacitance



APPLICATION NOTES

Power-Supply Considerations Overview

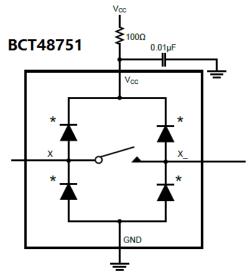
The BCT48751 construction is typical of most CMOS analog switch. It supports single power supply. V_{CC} and GND used to drive the internal CMOS switches and set the limits of the analog voltage on any switch. Reserve ESD protection diodes are internally connected between each analog-signal pin and both V_{CC} and GND. If any analog signal exceeds V_{CC} or GND, one of these diodes will conduct. During normal operation, these and other reverse-biased ESD diodes leak, forming the only current drawn from V_{CC} or GND.

Virtually all the analog leakage current comes from the ESD diodes. Although the ESD diodes on a given signal pin are identical and therefore fairly well balanced, they are reverse biased differently. Each is biased by either $V_{\rm CC}$ or GND and the analog signal. This means their leakages will vary as the signal varies. The difference in the two diode leakages to the $V_{\rm CC}$ and GND pins constitutes the analog-signal-path leakage current. All analog leakage current flows between each pin one of the supply terminals, not to the other switch terminal. This is why both sides of a given switch can show leakage currents of either the same or opposite polarity.

Over-Voltage Protection

Proper power-supply sequencing is recommended for the CMOS device. Do not

exceed the absolute maximum ratings because stresses beyond the listed ratings can cause permanent damage to the devices. Always sequence VCC on first, followed by the logic inputs and analog signals. If power-supply sequencing is not possible, add one 100 resistor in series with the supply VCC pin for over-voltage protection (Figure 1).



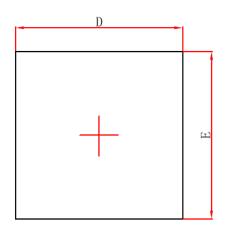
*INTERNAL PROTECTION DIODES

Figure 1. Over-Voltage Protection Using External Resistor

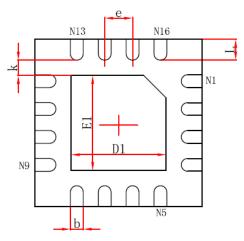


PACKAGE OUTLINE DIMENSIONS

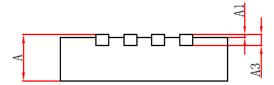
QFN3x3-16L



Top View



Bottom Vlew



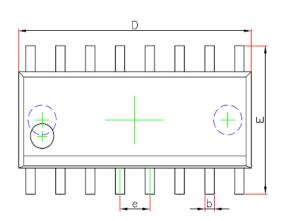
Side View

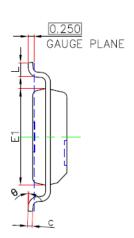
Cumbal	Dimensions Ir	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035	
A1	0.000	0.050	0.000	0.002	
А3	0.203	REF	0.008REF		
D	2.924	3.076	0.115	0.121	
Е	2.924	3.076	0.115	0.121	
D1	1.600	1.800	0.063	0.071	
E1	1.600	1.800	0.063	0.071	
k	0.200MIN.		0.008MIN.		
b	0.180	0.280	0.007	0.011	
е	0.500	OTYP. 0.020TYP.		OTYP.	
L	0.324	0.476	0.013	0.019	

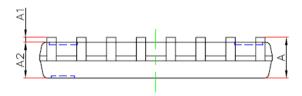
QFN3X3-16L Surface Mount Package



PACKAGE OUTLINE DIMENSIONS SOP16





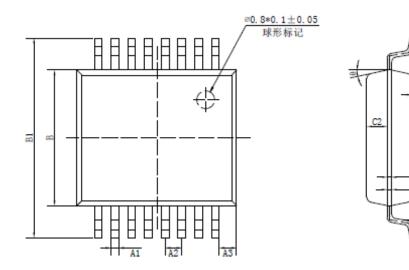


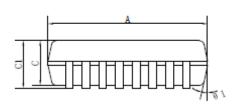
Symbol	Dimensions In M	illimeters	Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α		1.750		0.069	
A1	0.150	0.250	0.006	0.010	
A2	1.400	1.500	0.055	0.059	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.007	0.010	
D	9.800	10.000	0.386	0.394	
е	1.270(BSC)	C) 0.050(BSC)		
Е	5.900	6.100	0.232	0.240	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	O°	8°	

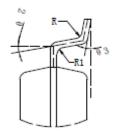
SOP16 Surface Mount Package



PACKAGE OUTLINE DIMENSIONS SSOP16







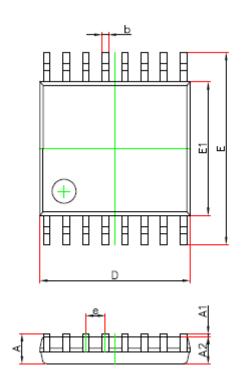
Symbol	Min	Max	Symbol	Min	Max
A	6.15	6.25	C3		152 TYP
A1	0.30		C4		172 TYP
A2	0.65		Н	0.05 0.06	
A3	0.675	TYP	θ	12° TYP	
В	5.25	5.35	θ 1	12° TYP	
B1	7.65	7.95	θ 2	10° TYP	
B2	0.60	0.80	θ 3	0°	8°
С	1.70	1.80	R	0.20 TYP	
C1	1.75	1.95	R1	0.15 TYP	
C2	0.799 TYP				

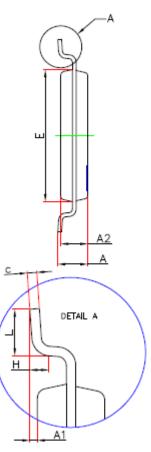
SSOP16 Surface Mount Package (unit: mm)



PACKAGE OUTLINE DIMENSIONS

TSSOP16





Symbol	Dimensions Ir	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	_	1.200		0.047	
A1	0.050	0.150	0.002	0.006	
A2	0.800	1.000	0.031	0.039	
b	0.190	0.300	0.007	0.012	
С	0.090	0.200	0.004	0.008	
D	4.900	5.100	0.193	0.201	
E	6.250	6.550	0.246	0.258	
E1	4.300	4.500	0.169	0.177	
е	0.650(BSC)	0.026	(BSC)	
L	0.500	0.700	0.020	0.028	
Н	0.250(TYP)	0.010(TYP)		
θ	1°	7°	1°	7°	

TSSOP16 Surface Mount Package

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PI5A392AQEX PI5A392AQE FSA634UCX NX3L1T5157GMZ ADG714BCPZ-REEL7 HT4051ARZ TC4066BP(N,F) DG302BDJ-E3

ADG854BCPZ-REEL7 PI5A100WE PI5A100QEX HV2733FG-G HV2701FG-G HV2301FG-G HV2301FG-G-M931 RS2117YUTQK10

RS2118YUTQK10 RS2227XUTQK10 ADG452BRZ-REEL7 MAX391CPE+ MAX4744ELB+ MAX4730EXT+T MAX4730ELT+

MAX333AEWP+ BU4066BC MAX313CPE+ BU4S66G2-TR NLASB3157MTR2G NX3L4684TK,115 NX5L2750CGUX

NLAS4157DFT2G NLAS4599DFT2G NLASB3157DFT2G NLAST4599DFT2G NLAST4599DTT1G